

Amendments to the Claims:

No claims have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Previously Presented) A method of enhancing adhesion of a compound to a surface of a substrate comprising:
providing the substrate having the surface;
scanning the substrate for irregularities for removal; and
roughening the surface of the substrate for removal of irregularities.
2. (Previously Presented) The method according to claim 1, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.
3. (Previously Presented) A method of enhancing adhesion of a material to a surface of a substrate comprising:
providing the substrate having the surface;
scanning the substrate for irregularities for removal; and
roughening the surface of the substrate while removing irregularities.
4. (Previously Presented) The method according to claim 3, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.

5. (Previously Presented) A method for improving adhesion of a compound to a surface of a substrate comprising:

providing the substrate having the surface;

scanning the substrate for irregularities for removal; and

roughening the surface of the substrate.

6. (Previously Presented) The method according to claim 5, wherein roughening comprises removing contamination and foreign particles from the surface of the substrate.